



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-06
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L5965SQ-V0T	A9V0*UAW5CA1	A	997G	2018-09-06
	Amount	UoM	Unit type	ST ECOPACK Grade
	130	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x1	48	No lead	
Comment	Package: VFQFPN 7x7x1.0 48 PITCH 0.5; MDF valid also for L5965SQ-V0Y			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.11	Die	877

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
-	-			0
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
-	-	0.00		

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A9V0*UAWSCA1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	16.325	mg	supplier	die	Silicon (Si)	7440-21-3		14.900	mg	912711	114615
				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	2144	269
				supplier	metallization	Copper (Cu)	7440-50-8		0.923	mg	56539	7100
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	61	8
				supplier	passivation	Nickel (Ni)	7440-02-0		0.114	mg	6983	877
				supplier	metallization	Platinum (Pt)	7440-06-4		0.064	mg	3920	492
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	368	46
				supplier	metallization	Tungsten (W)	7440-33-7		0.053	mg	3246	408
				supplier	Passivation	Silicon Oxide	7631-86-9		0.229	mg	14028	1762
				supplier	alloy	Copper (Cu)	7440-50-8		46.665	mg	972937	358962
Leadframe	M-004 Copper and its alloys	47.963	mg	supplier	alloy	Chromium (Cr)	7440-47-3		0.127	mg	2649	977
				supplier	alloy	Tin (Sn)	7440-31-5		0.117	mg	2439	900
				supplier	alloy	Zinc (Zn)	7440-66-6		0.094	mg	1960	722
				supplier	metallization	Silver (Ag)	7440-22-4		0.960	mg	20015	7385
				supplier	glue	Silver (Ag)	7440-22-4		3.527	mg	814738	27131
				supplier	glue	[Octahydro-4,7-methano-1 H-indenediyl]bis(methoxy)ethane	42594-17-2		0.260	mg	60060	2000
Die attach	M-011 Other inorganic materials	4.329	mg	supplier	glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3		0.260	mg	60060	2000
				supplier	glue	Isobornyl acrylate	5888-33-5		0.260	mg	60060	2000
				supplier	glue	Bis(alpha,alpha-Dimethylbenzyl) peroxide	80-43-3		0.022	mg	5082	169
				supplier	wire	Gold (Au)	7440-57-5		1.822	mg	1000000	14015
Bonding wire	M-008 Precious metals	1.822	mg	supplier	wire	Gold (Au)	7440-57-5		1.822	mg	1000000	14015
				supplier	mold compound	Silica, vitreous	60676-86-0		50.202	mg	904997	386169
				supplier	mold compound	Epoxy Resin	25068-38-6		2.607	mg	46997	20054
				supplier	mold compound	Phenol Resin	29960-82-2		2.607	mg	46997	20054
Encapsulation	M-011 Other inorganic materials	55.472	mg	supplier	mold compound	Carbon black	1333-86-4		0.056	mg	941	431
				supplier	solder alloy	Tin (Sn)	7440-31-5		4.089	mg	1000000	31454
connections coating	Solder	4.089	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.089	mg	1000000	31454